

MTW54N05E-VB Datasheet N-Channel 60 V (D-S) MOSFET

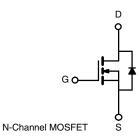
PRODUCT SUMMARY					
V _{DS} (V)	60				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.007				
I _D (A)	150				
Configuration	Single				
Package	TO-247				

FEATURES

- Trench power MOSFET
- Package with low thermal resistance
- 100 % $\rm R_g$ and UIS tested







ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \text{ °C}$, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	60	V			
Gate-Source Voltage	V _{GS}	± 20	V			
Continuous Drain Current	T _C = 25 °C	I	150			
	T _C = 125 °C	- I _D	88			
Continuous Source Current (Diode Condu	I _S	120	А			
Pulsed Drain Current ^b	I _{DM}	480				
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	65			
Single Pulse Avalanche Energy		E _{AS}	211	mJ		
Mauianum Daura Diasia atian b	T _C = 25 °C	T _C = 25 °C		W		
Maximum Power Dissipation ^b	T _C = 125 °C	P _D	56	vv		
Operating Junction and Storage Temperat	T _J , T _{stq}	-55 to +175	°C			

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	LIMIT	UNIT			
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W			
Junction-to-Case (Drain)	R _{thJC}	0.88	0/11				

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static		•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \ \mu A$		60	-	-	v	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.5	3.0	3.5	v	
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, $V_{GS} = \pm 20 V$	-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	250	1	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.007	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 V$	$I_D = 30 \text{ A}, \text{T}_\text{J} = 125 \ ^\circ\text{C}$	-	0.010	-	Ω	
		$V_{GS} = 10 V$	I _D = 30 A, T _J = 175 °C	-	0.013	-	1	
Forward Transconductance b	g _{fs}	V _{DS} = 15 V, I _D = 30 A		-	94	-	S	
Dynamic ^b	- -	·						
Input Capacitance	C _{iss}			-	5196	-		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V_{DS} = 25 V, f = 1 MHz	-	710	-	pF	
Reverse Transfer Capacitance	C _{rss}]		-	340	-		
Total Gate Charge ^c	Qg			-	97	-		
Gate-Source Charge ^c	Q _{gs}	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, I_D = 75 \text{ A}$	-	24.6	-	nC	
Gate-Drain Charge ^c	Q _{gd}]		-	27.2	-		
Gate Resistance	Rg		f = 1 MHz		1	1.7	Ω	
Turn-On Delay Time ^c	t _{d(on)}				16	24	- ns	
Rise Time ^c	t _r	$\begin{array}{l} V_{\text{DD}}=\text{30 V, R}_{\text{L}}=\text{0.4 }\Omega\\ I_{\text{D}}\cong\text{75 A, V}_{\text{GEN}}=\text{10 V, R}_{\text{g}}=\text{1 }\Omega \end{array}$		-	14	21		
Turn-Off Delay Time ^c	t _{d(off)}			-	34	51		
Fall Time °	t _f]	-	9	14			
Source-Drain Diode Ratings and Chara	acteristics ^b	<u> </u>			•			
Pulsed Current ^a	I _{SM}			-	-	480	А	
Forward Voltage	V _{SD}	I _F :	-	0.9	1.5	V		

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

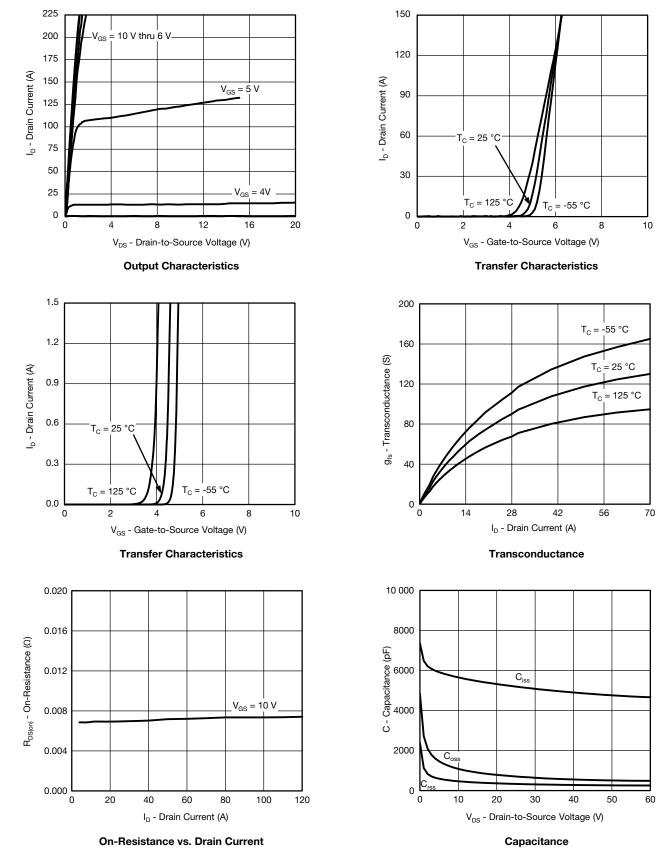
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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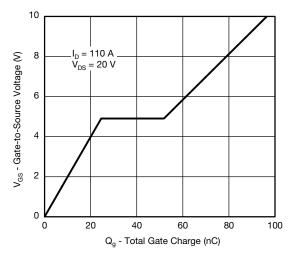


TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

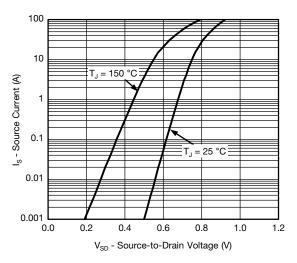




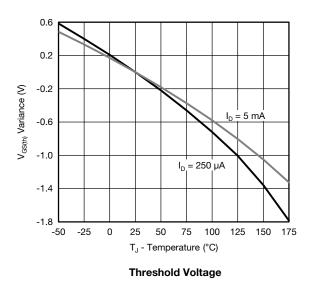
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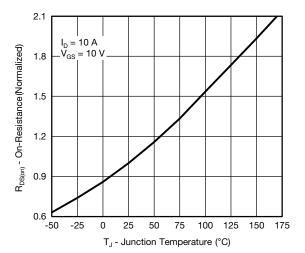


Gate Charge

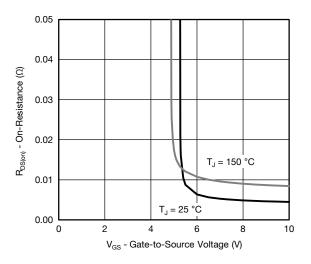


Source Drain Diode Forward Voltage

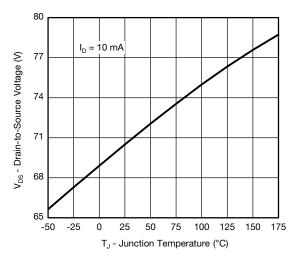




On-Resistance vs. Junction Temperature



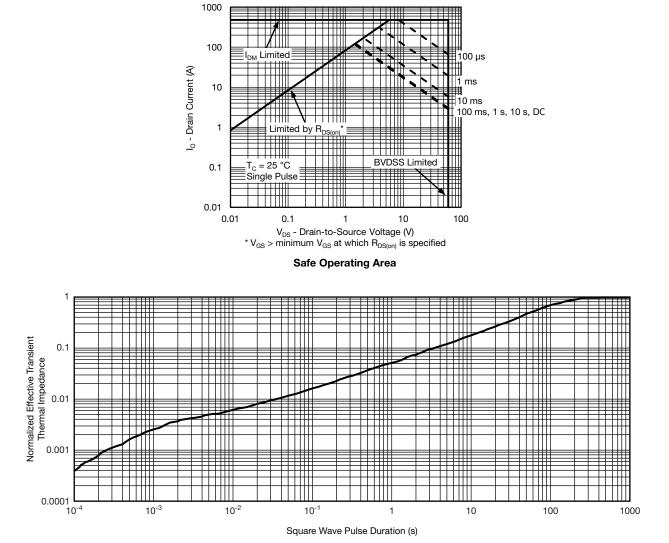
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



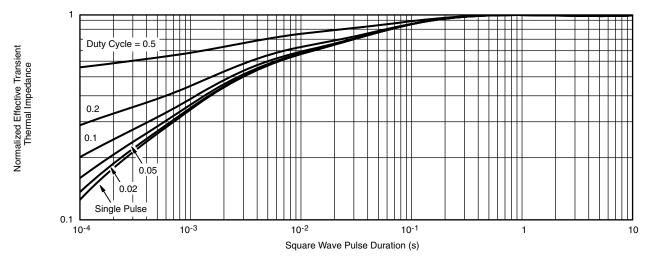
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



0.602

0.540

0.559 0.146

0.138

-0.209

0.178

0.625

-

0.640

0.169

0.144 0.291

0.224

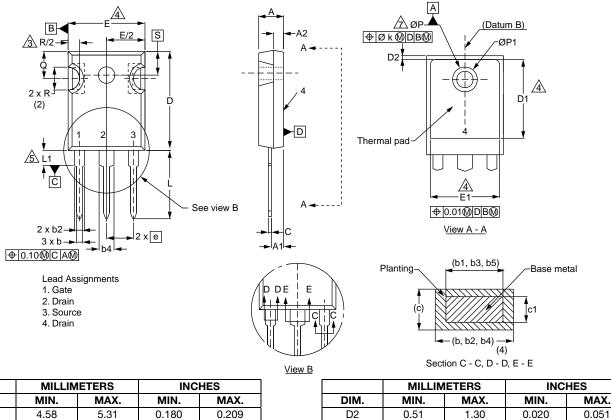
0.216

0.215 BSC 0.010

0.300 BSC

0.217 BSC

TO-247AC



	MILLIN	IETERS	INC	HES			MILLIN	IETERS
DIM.	MIN.	MAX.	MIN.	MAX.]	DIM.	MIN.	MAX.
А	4.58	5.31	0.180	0.209		D2	0.51	1.30
A1	2.21	2.59	0.087	0.102		E	15.29	15.87
A2	1.17	2.49	0.046	0.098		E1	13.72	-
b	0.99	1.40	0.039	0.055		е	5.46 BSC	
b1	0.99	1.35	0.039	0.053		Øk	0.254	
b2	1.53	2.39	0.060	0.094		L	14.20	16.25
b3	1.65	2.37	0.065	0.093		L1	3.71	4.29
b4	2.42	3.43	0.095	0.135		N	7.62 BSC	
b5	2.59	3.38	0.102	0.133		ØΡ	3.51	3.66
с	0.38	0.86	0.015	0.034		Ø P1	-	7.39
c1	0.38	0.76	0.015	0.030		Q	5.31	5.69
D	19.71	20.82	0.776	0.820		R	4.52	5.49
D1	13.08	-	0.515	-		S	5.51 BSC	



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